

# Bill of Materials

**TI DESIGNS**

Automotive Acoustic Knock Sensor Interface

COUNT	REF DES	DESCRIPTION	SIZE	MFR	PART NUMBER
2	C1, C2	Capacitor, ceramic, 3300pF, 50V, 10%	603	muRata	GRM188R71H332KA01D
3	C3, C5, C6	Capacitor, ceramic, 0.1uF, 50V, 10%	603	muRata	GRM188R71H104KA93D
1	C4	Capacitor, ceramic, 4.7uF, 16V, 10%	1206	muRata	GRM31CR61C475KA01L
1	C7	Capacitor, ceramic, 470pF, 50V, 10%	603	muRata	GRM188R71H471KA01D
1	J1	Dual row header right angle, 30-pin, 100-mil spacing, (80-pin strip)	0.100 x 15	Tyco	9-146308-0
3	5V, INH/H, TCLK	Header, 2-pin, 100-mil spacing, (36-pin strip)	0.100 x 2	Sullins	PEC02SAAN
3	5V, INH/H, TCLK	Connector jumper, shorting, 100-mil spacing	0.1	Sullins	SPC02SYAN
4	R1, R2, R3, R4	Resistor, chip, 30.1 kW, 1/10W, 1%	603	Panasonic	ERJ-3EKF3012V
1	R5	Resistor, chip, 1 kW, 1/10W, 1%	603	Panasonic	ERJ-3EKF1001V
1	R6	Resistor, chip, 1 MW, 1/10W, 1%	603	Panasonic	ERJ-3EKF1004V
1	R7	Resistor, chip, 0 W, 1/10W, 1%	603	Panasonic	ERJ-3GEY0R00V
19	CH1, CH1FB, CH1N, CH2, CH2FB, CH2N, CS/, GND (x3), OUT, SCLK, SDI, SDO, TEST, VIN, VREF, XCLK	Test point, 52-mil	0.052	Kobiconn	151-103-RC
1	U1	IC, TPIC8101DW		TI	TPIC8101DW
1	-	PCB, 1.6-inch x 1.9-inch x 0.062		Any	TPIC8101, REV B

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